



# SPECIFICATION FOR APPROVAL

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CUSTOMER	
NOMINAL FREQUENCY	8.000000 MHz
HOLDER TYPE	TYPE FY 5.0x3.2 SEAM SEALED CRYSTAL
SPEC. NO. ( P/N )	FY0800024Q
CUSTOMER P/N	
ISSUE DATE	September 4, 2018
VERSION	C

APPROVED	PREPARED	QA	
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# **Diodes Incorporated**

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- \*Pb-free
- \*RoHS Compliant
- \*HF-Halogen Free
- \*REACH Compliant
- \*AEC-Q200 Compliant

E0-R-4-014 Rev. F

FY0800024Q

VER. C 4-Sep-18

# **VERSION HISTORY**

Version No.	Version Date	Description	Notes
Α	Oct.3,2011	Initial Release	
В	Mar.6,2017	1.Updated reliability test spec & Added AEC-Q200 Compliant on cover page  2.Revised Maximum Drive Level	
С	Sep.4,2018	Updated logo	

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### **ELECTRICAL SPECIFICATIONS**

Item	Symbol	<b>Specifications</b>	Units	Notes
Nominal Frequency	Fn	8.000000	MHz	
Mode of Oscillation	МО	AT Cut-Fundamental		
Calibration Load Capacitance	CL	20	pF	
Calibration Tolerance	FL	±20	ppm	at 25℃±3℃
Operating Temperature Range	TR	-40 to +125	C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±75	ppm	Reference to the Frequency at 25℃
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	100	Ω	Max
Shunt Capacitance	C0	5	pF	Max
Aging at 25℃		±5	ppm	Max, 1st year
Storage Temperature		-55 to +125	C	
Insulation Resistance		500	МΩ	Min

★ This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).

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#### **AEC-Q200 RELIABILITY TEST SPECIFICATIONS:**

#### 1. Initial

- 1.1 Physical Dimensions: JESD22, Method JB1-100
- 1.2 External Visual: MIL-STD-883, Method 2009
- 1.3 Freq. Vs. Temperature: Per Specification/Datasheet

#### 2. Mechanical

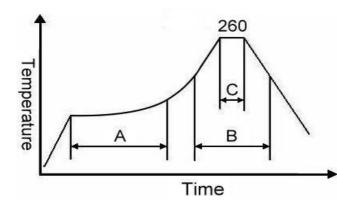
- 2.1 Mechanical Shock: MIL-STD-202 Method 213
- 2.2 Vibration: MIL-STD-202 Method 204
- 2.3 Solderability: J-STD-002
- 2.4 Board Flex: AEC Q200-005
- 2.5 Terminal Strength (SMD): AEC Q200-006

#### 3.Environmental

- 3.1 Temp Cycle: JESD22, Method JA-104
- 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210
- 3.3 High Temperature Operating Life: MIL-STD-202, Method 108
- 3.4 High Temp Exposure: MIL-STD-202, Method 108
- 3.5 High Temp & High Humidity: MIL-STD-202, Method 103
- 3.6 Thermal Shock: MIL-STD-202, Method 107

## SUGGESTED IR REFLOW PROFILE

\*As per IPC-JEDEC J-STD-020D



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1.3	u	L	•	-	

	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec

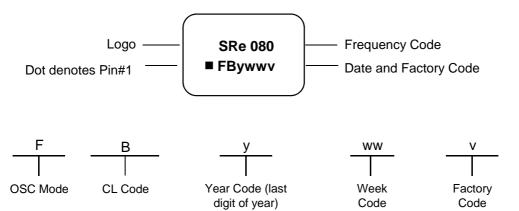


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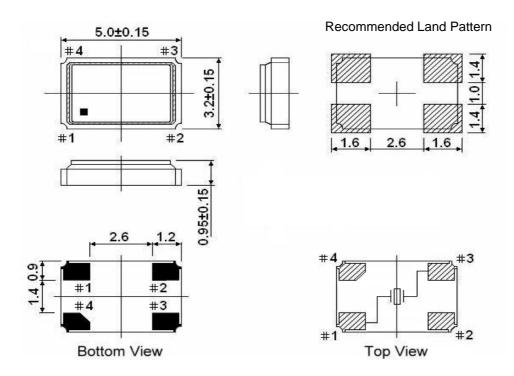
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#### **MARKING**



## MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)



\*\* Recommended - Pin 1 & 3 : CRYSTAL Pin 2 & 4 : GND

#### Notes:

- Package drawings are for reference only, and the appearances of objects may vary.
  Actual packages are based on the real product.
- 2. The marking dot denotes Pin#1.
- 3. The position and shape of the chamfer pin may vary and are based on the real product.

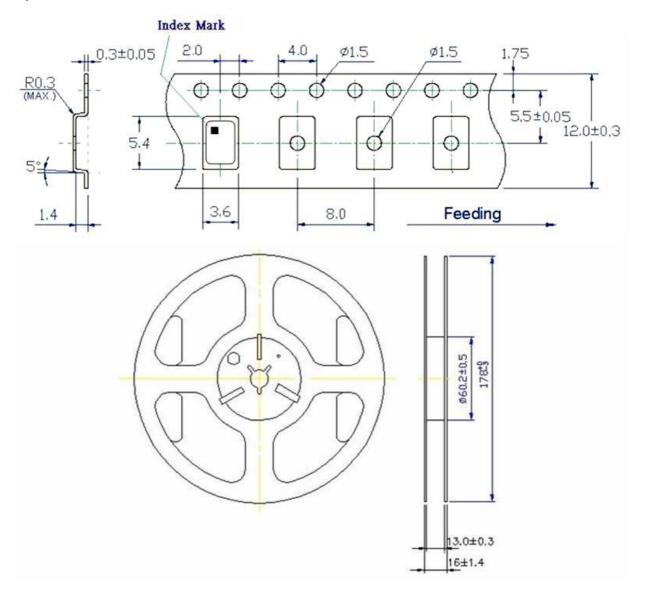
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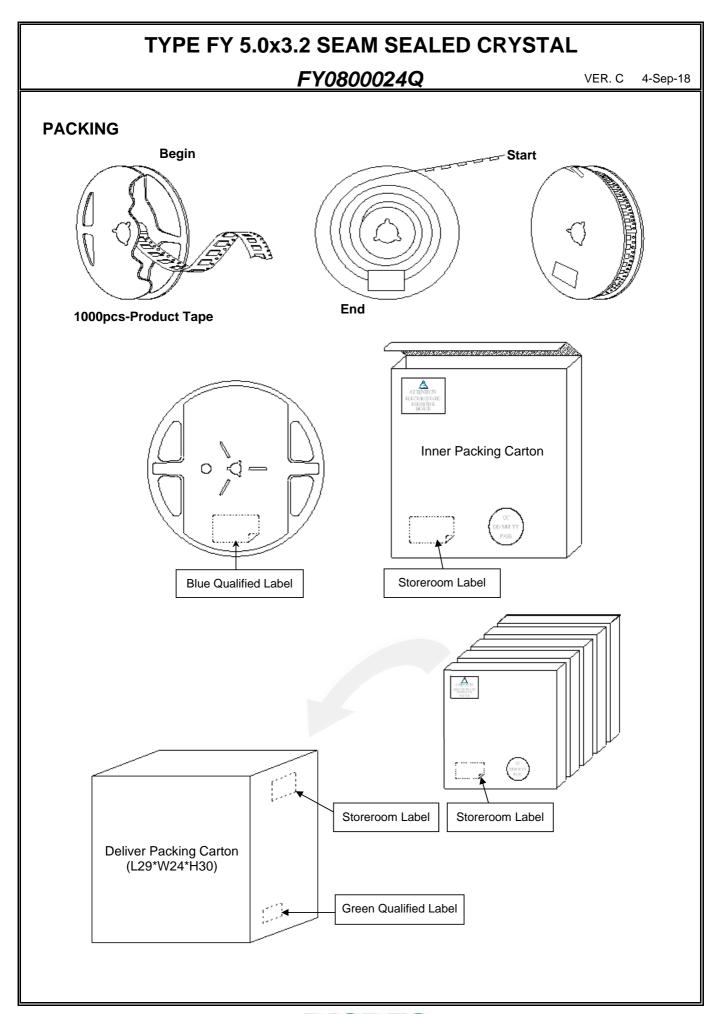
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## Tape & Reel



- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

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